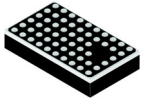


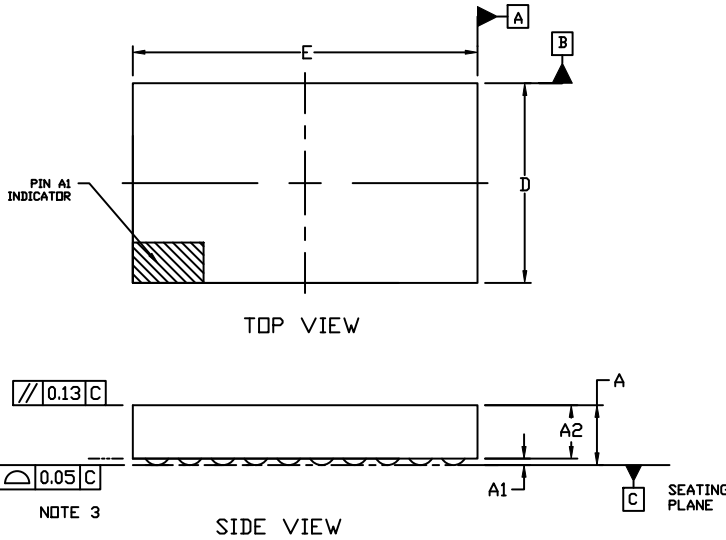
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



SIP57 6.80x3.94
CASE 127EX
ISSUE B

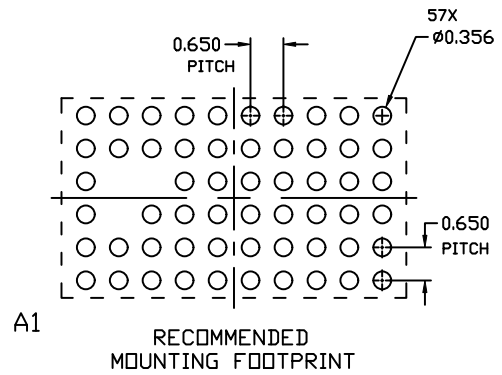
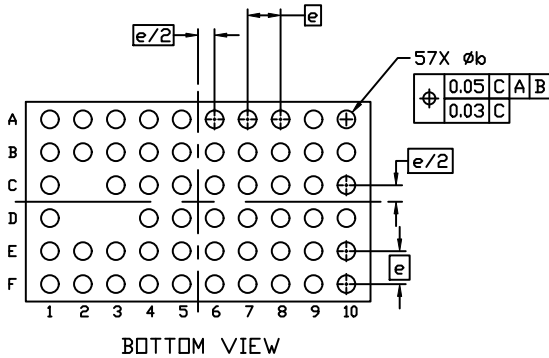
DATE 10 MAR 2022



NOTES:

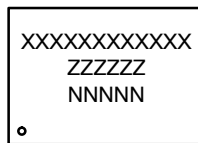
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE PADS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.275
A1	0.075	0.150
A2	1.025	1.125
b	0.300	0.400
D	3.815	4.065
E	6.675	6.925
e	0.650 BSC	



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
ZZZ = Assembly Lot Code
NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SIP57 6.80x3.94	PAGE 1 OF 1

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